

低誘電・低誘電正接 熱硬化型絶縁材料ドライフィルム

Low Dk · Low Df Thermal Curable Dry Film Build-up Material



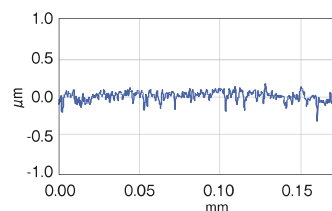
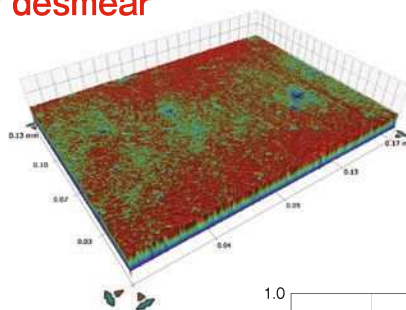
熱硬化型絶縁材料ドライフィルム Zaristo Series

Thermal Curable Dielectric Dry Film Zaristo Series

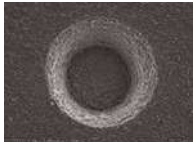
特長 Features

- **エポキシ系では到達困難な誘電特性**
Excellent dielectric property which is difficult for epoxy type material
- **低誘電率、低誘電正接**
Low Dk, low Df
- **低吸水性**
low water absorption
- **低粗度、高密着**
Low roughness, high adhesion
- **高Tg**
High Tg

Surface roughness After desmear



特性 Properties

Ra(After desmear)	50~100nm	
Peel strength	Initial	>4.0N/cm
	85°C85%100hrs	>3.5N/cm
After Desmear of Laser Via		Top:63μm Bottom:45μm Taper ratio:71%

	Zaristo 700 (TR76401)
Features	Low Dk, Df film(non Epoxy type)
TMA Tg (deg.C)	185-195
CTE α1/α2(ppm)	15-20/90-100
Dk @10GHz	3.1-3.2
Df @10GHz	0.0013-0.0015
Water absorption (%)	0.03
Ra after Desmear (μm)	<0.1
Peel Strength (N/cm)	3.5-5.0

用途 Application

- **次世代移動体通信システム**
Next generation mobile communication system
- **無線通信基地局**
Wireless communication station